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Product Change Notification - JAON-16TUGT945

Date: 02 Oct 2016
Product Category: Memory
Notification subject: CCB 2652 Final Notice: Qualification of G600V molding compound for products available in 8L SOIC Chip On Lead (COL) package assembled at MTAI assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of G600V molding compound for products available in 8L SOIC Chip On Lead (COL) package assembled at MTAI assembly site.

Pre Change:

Using SG-8300GM molding compound

Post Change:

Using G600V molding compound

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	Au wire
Die attach material	8006NS	8006NS
Molding compound material	SG-8300GM	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying G600V molding compound.

Change Implementation Status:
In Progress

Estimated First Ship Date:
October 17, 2016 (date code: 1642)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	June 2016					-->	September 2016					October 2016			
	22	23	24	25	26		35	36	37	38	39	40	41	42	43
Initial PCN Issue Date				X											
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date													X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
June 21, 2016: Issued initial notification.
October 2, 2016: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on October 17, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-16TUGT945_Qual Report.pdf](#)
 - [PCN_JAON-16TUGT945_Affected CPN.pdf](#)
 - [PCN_JAON-16TUGT945_Affected CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-16TUGT945
CATALOG_PART_NBR
23A1024-E/SN
23A1024-I/SN
23A1024T-E/SN
23A1024T-I/SN
23A512-E/SN
23A512-I/SN
23A512T-E/SN
23A512T-I/SN
23LC1024-E/SN
23LC1024-I/SN
23LC1024T-E/SN
23LC1024T-I/SN
23LC512-E/SN
23LC512-I/SN
23LC512T-E/SN
23LC512T-I/SN
23LCV1024-I/SN
23LCV1024T-I/SN
23LCV512-I/SN
23LCV512T-I/SN
24AA128-I/SN
24AA128T-I/SN
24AA512-I/SN
24AA512T-I/SN
24FC128-I/SN
24FC128T-I/SN
24FC512-I/SN
24FC512T-I/SN
24LC128-I/SN
24LC128T-I/SN
24LC256-I/SN
24LC256T-I/SN
24LC512-E/SN
24LC512-I/SN
24LC512T-E/SN
24LC512T-I/SN
25AA128-I/SN
25AA128T-I/SN
25AA256-I/SN
25AA256T-I/SN
25LC128-E/SN
25LC128-I/SN
25LC128T-E/SN

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Affected Catalog Part Numbers (CPN)

PCN_JAON-16TUGT945
CATALOG_PART_NBR
25LC128T-I/SN
25LC256-I/SN
25LC256T-I/SN